

Contents

<i>Contributors</i>	ix
<i>Preface</i>	xi
1 Plasma Etching Technology—An Overview	1
<i>Daniel L. Flamm and G. K. Herb</i>	
I. Introduction	2
II. What Is a Plasma?	14
III. Processes in a Plasma	20
IV. Process Requirements and Examples	42
V. Plasma Reactors	64
VI. Etching Endpoint Detection	73
VII. Device Damage from the Plasma	82
References	87
2 Introduction to Plasma Chemistry	91
<i>Daniel L. Flamm</i>	
I. Overview	92
II. How Plasma Etching Takes Place	92
III. Etching Characteristics and Variables	99
IV. Etching Silicon in Fluorine Atom Based Plasmas	131
V. The Loading Effect	138
VI. The Role of Gas Additives	144
VII. Chlorine Plasma Etching	146
VIII. Etchant-Unsaturate Concepts	155
IX. Etching Silicon Oxide in Unsaturated and Fluorine-Rich Plasmas	159
X. Silicon Nitride Etching	165
XI. Oxygen Plasma Etching of Resists	167
XII. III-V Etching Chemistries and Mechanisms	170
Acknowledgement	178
References	178

3 An Introduction to Plasma Physics for Materials Processing	185
<i>Samuel A. Cohen</i>	
I. Introduction	186
II. The Plasma State	187
III. Single-Particle Motion	193
IV. Plasma Parameters	205
V. Discharge Initiation	241
VI. An Application—The Planar Magnetron	248
Acknowledgements	258
References	258
4 Diagnostics of Plasmas for Materials Processing	259
<i>D. M. Manos and H. F. Dylla</i>	
I. Introduction	260
II. Electrostatic (Langmuir) Probes	261
III. Microwave Interferometry	289
IV. Impedance Analysis	297
V. Mass Spectrometry of Plasmas	305
VI. Emission Spectroscopy	312
VII. Fluorescence	325
VIII. Summary	331
References	332
5 Plasma Etch Equipment and Technology	339
<i>Alan R. Reinberg</i>	
I. Introduction	340
II. Classification of Etch Equipment	341
III. Process Control	354
IV. Etching Methods—Films	359
V. Etching Techniques	363
VI. Other Materials	384
VII. Discovering and Characterizing Processes	385
References	387
6 Ion Beam Etching	391
<i>James M. E. Harper</i>	
I. Introduction	391
II. Broad-Beam Ion Sources	392
III. Inert Ion Beam Etching	404
IV. Reactive Ion Beam Etching	411

V. Ion Etching Combined with Growth or Deposition	418
Acknowledgements	421
References	421
7 Safety, Health, and Engineering Considerations for Plasma Processing	425
<i>G. K. Herb</i>	
I. Legislated Safety Obligations	426
II. Response to Safety Legislation	429
III. Plasma Process Chemistry	434
IV. Characteristics of Cylinder Gases	437
V. Hazardous Gas Monitoring Instruments	443
VI. Checking the Workplace for Hazardous Chemicals	445
VII. A Hazardous Aluminum Plasma Etch Process	446
VIII. Plasma Process System Configuration	451
IX. Recommendations	462
Appendix A: Comparison of Federal and State Occupational Safety and Health Requirements	463
Appendix B: Characteristics of Common Plasma Etch Feeds	465
References	468
Index	471